/ Revised record

SOD-323

Parameter	Symbol	Rating	Unit
Maximum recurrent peak reverse voltage	V_{RM}	45	V
DC reverse voltage	V_R	40	V

Continuous forward current

/ Electrical Characteristic Curve

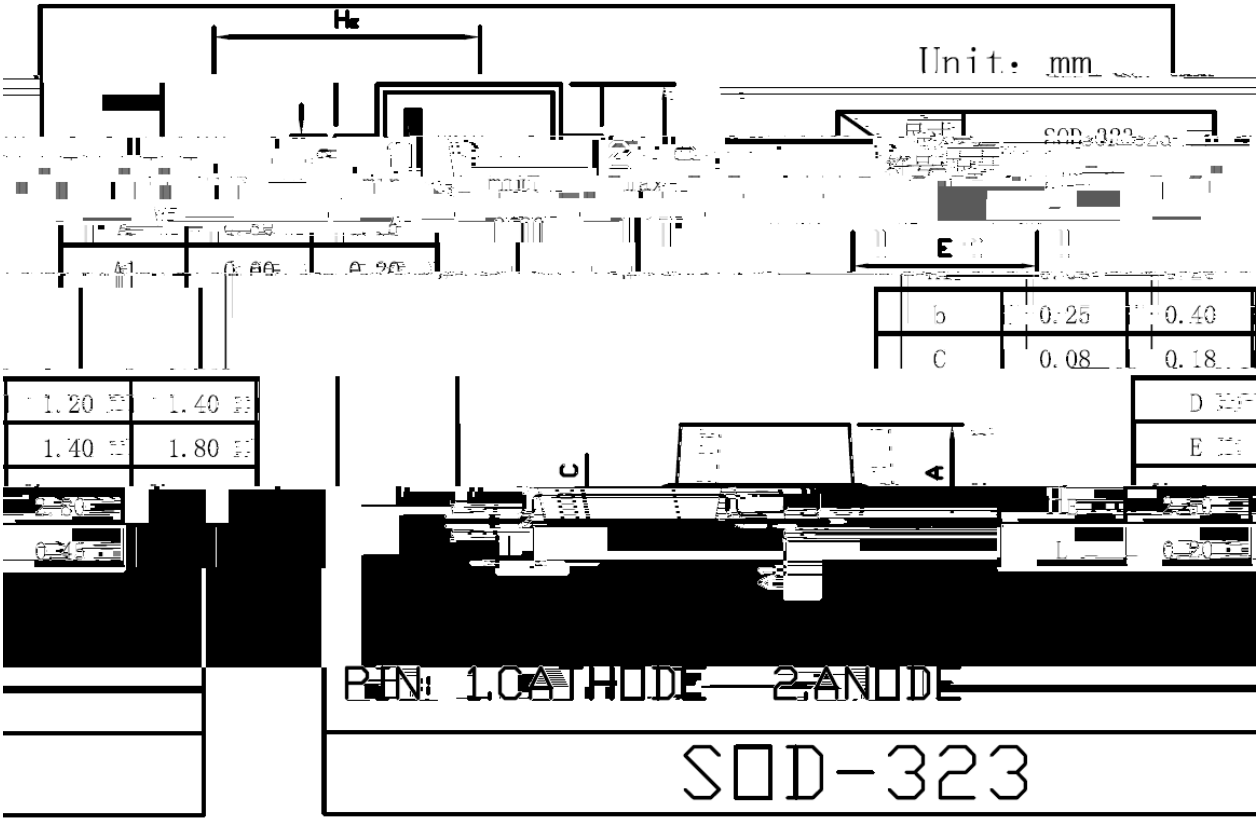
Fig.1

Fig.3 TYPICAL FORWARD VOLTA

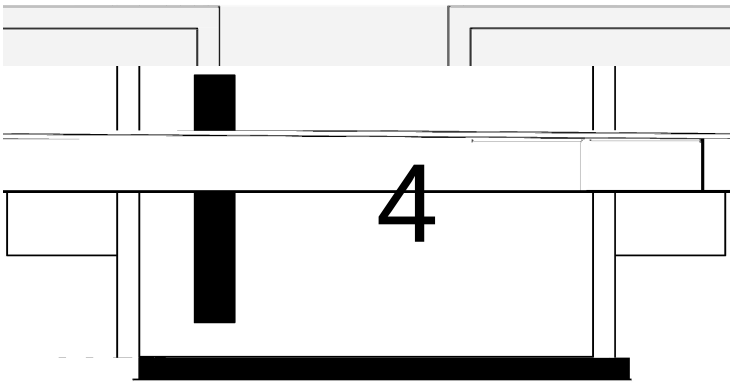
1000

Fig.4 Typical Junction Capacitance

/ Package Dimensions



/ Marking Instructions



4

Note:

4 : Product Type.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 150～180℃，时间 60～90sec;

2、峰值温度 245±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:150~180℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type	Units			Units/Outer Box	Dimension (unit mm³)		
	只/卷盘	卷盘/盒	只/盒	只/箱	Reel	Inner Box	Outer Box

ackaging